



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



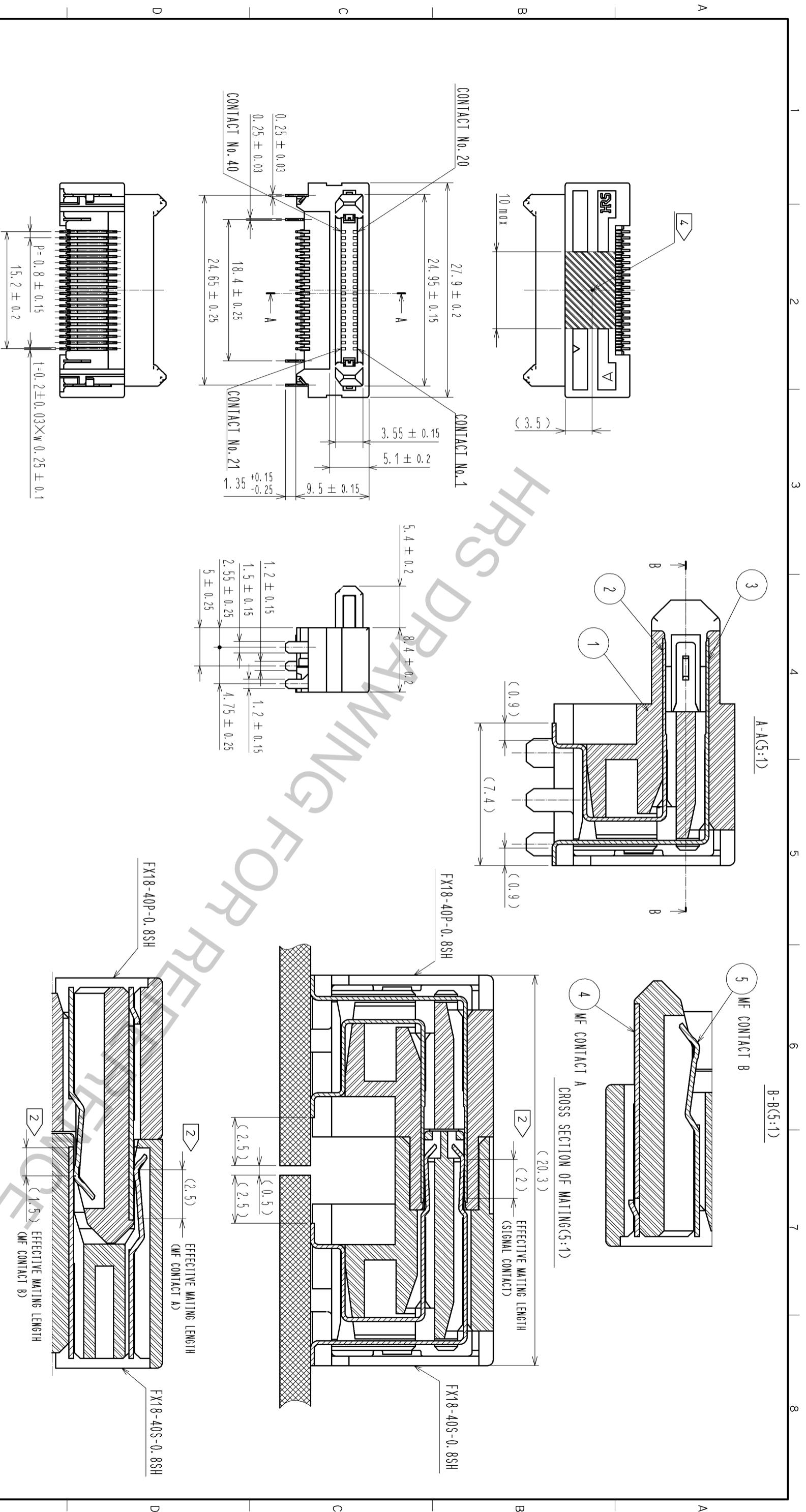
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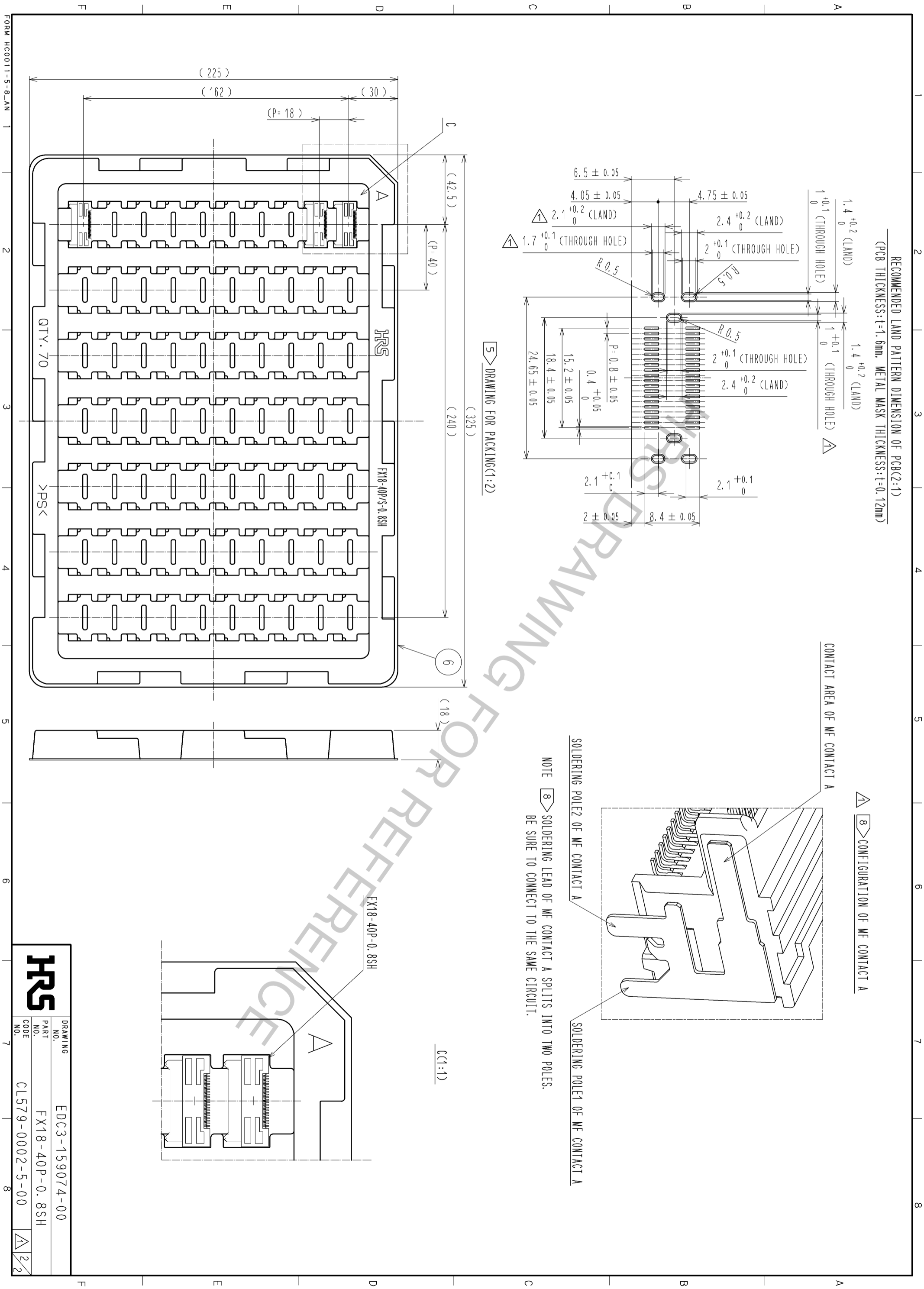
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





- NOTE
- LEAD CO-PLANARITY IS 0.1mm MAX.
 - CONTACTS ARE 3 STEPS SEQUENTIAL. (MF CONTACT A->SIGNAL CONTACT->MF CONTACT B) WHEN USING THIS SEQUENTIAL STRUCTURE, PLEASE AVOID ANGLED INSERTION.
 - MF CONTACT A AND MF CONTACT B CAN BE USED AS POWER SUPPLY CONTACT. (3A/PIN MAX)
 - IT SHOWS CONNECTOR'S CENTRE OF GRAVITY AND VACUUM PICKUP AREA.
 - THIS IS PACKAGED IN TRAY. (70pcs/TRAY)
 - BLEMISH AND HIT MARK CAN BE OCCURED THROUGH OUT THE MANUFACTURING PROCESS WHICH DOESN'T AFFECT QUALITY LEVEL.
 - THE DIMENSIONS IN PARENTHESES ARE FOR REFERENCES.

NO.	1	2	3	4	5	6
MATERIAL	POLYAMIDE	PHOSPHOR BRONZE	PHOSPHOR BRONZE	PHOSPHOR BRONZE	POLYSTYRENE	
FINISH	UL94V-0	BLACK	CONTACT AREA: GOLD 0.14µm LEAD AREA: GOLD 0.03µm UNDER PLATING: NICKEL 1.3µm	CONTACT AREA: GOLD 0.14µm LEAD AREA: GOLD 0.03µm UNDER PLATING: NICKEL 1.3µm	CONTACT AREA: GOLD 0.14µm LEAD AREA: TIN-PLATING 1µm UNDER PLATING: NICKEL 1.3µm	CONTACT AREA: GOLD 0.14µm LEAD AREA: TIN-PLATING 1µm UNDER PLATING: NICKEL 1.3µm
REMARKS						
FINISH						
REMARKS						
NO.						
MATERIAL						
FINISH						
REMARKS						
SCALE	2:1					
COUNT	4					
DESCRIPTION OF REVISIONS	DIS-F-005578					
NO.						
DESIGNED	TH. SANNO					
CHECKED	KI. HIROKAWA					
DESIGNED	TH. SANNO					
CHECKED	KI. HIROKAWA					
NO.						
DRAWING	EDC3-159074-00					
PART	FX18-40P-0.8SH					
CODE	CL579-0002-5-00					
DATE	11.07.21					



RECOMMENDED LAND PATTERN DIMENSION OF PCB(2:1)
 (PCB THICKNESS:t=1.6mm, METAL MASK THICKNESS:t=0.12mm)

5 DRAWING FOR PACKING(1:2)

8 CONFIGURATION OF MF CONTACT A

CONTACT AREA OF MF CONTACT A

NOTE 8 SOLDERING LEAD OF MF CONTACT A SPLITS INTO TWO POLES. BE SURE TO CONNECT TO THE SAME CIRCUIT.

SOLDERING POLE2 OF MF CONTACT A

SOLDERING POLE1 OF MF CONTACT A

C(1:1)

FORM HC0011-5-8_AN

HRS	DRAWING NO.	EDC3-159074-00
	PART NO.	FX18-40P-0.8SH
	CODE NO.	CL579-0002-5-00

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